

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Takayama et al.
Serial No.: 10/672,521
Filed: September 26, 2003
For: Wiring Material, Semiconductor Device
Provided With A Wiring Using The Wiring
Material And Method of Manufacturing
Thereof
Examiner: Cheung Lee
Art Unit: 2812

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT F (AFTER FINAL)

In response to the Final Rejection of July 20, 2006, a RCE being filed herewith, please amend the above-identified application as follows: